



# SOT389-1

plastic low profile quad flat package; 44 leads; body 10 x 10 x 1.4 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	LQFP44
<b>Package type industry code</b>	LQFP44
<b>Package style descriptive code</b>	LQFP (low profile quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	136E08
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	7-6-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A <sub>2</sub>	package height	1.35	-	1.4	1.45	mm
n <sub>2</sub>	actual quantity of termination	-	-	44	-	

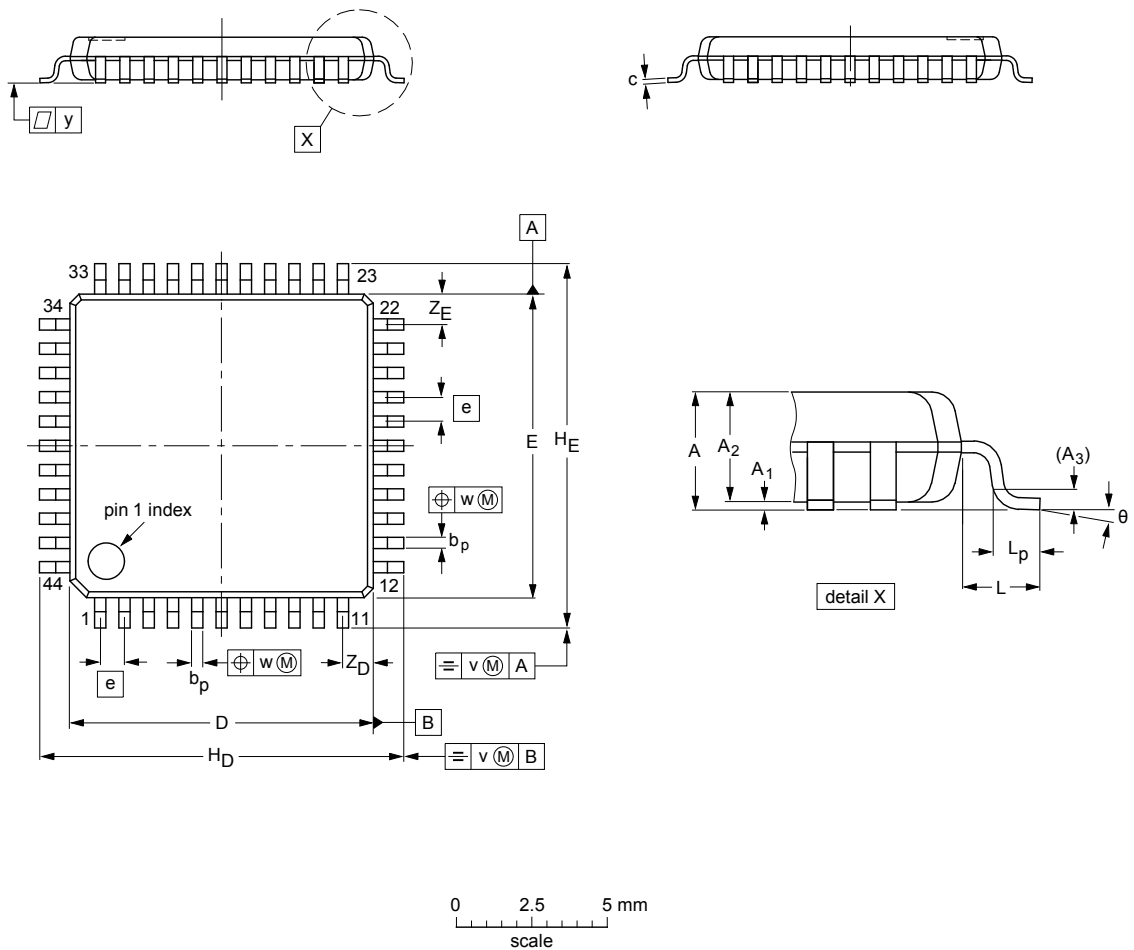


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2. Package outline

LQFP44: plastic low profile quad flat package; 44 leads; body 10 x 10 x 1.4 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.45 0.30	0.20 0.12	10.1 9.9	10.1 9.9	0.8	12.15 11.85	12.15 11.85	1	0.75 0.45	0.2	0.2	0.1	1.14 0.85	1.14 0.85	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT389-1	136E08	MS-026				-00-04-19- 02-06-07

Fig. 1. Package outline LQFP44 (SOT389-1)

### 3. Soldering

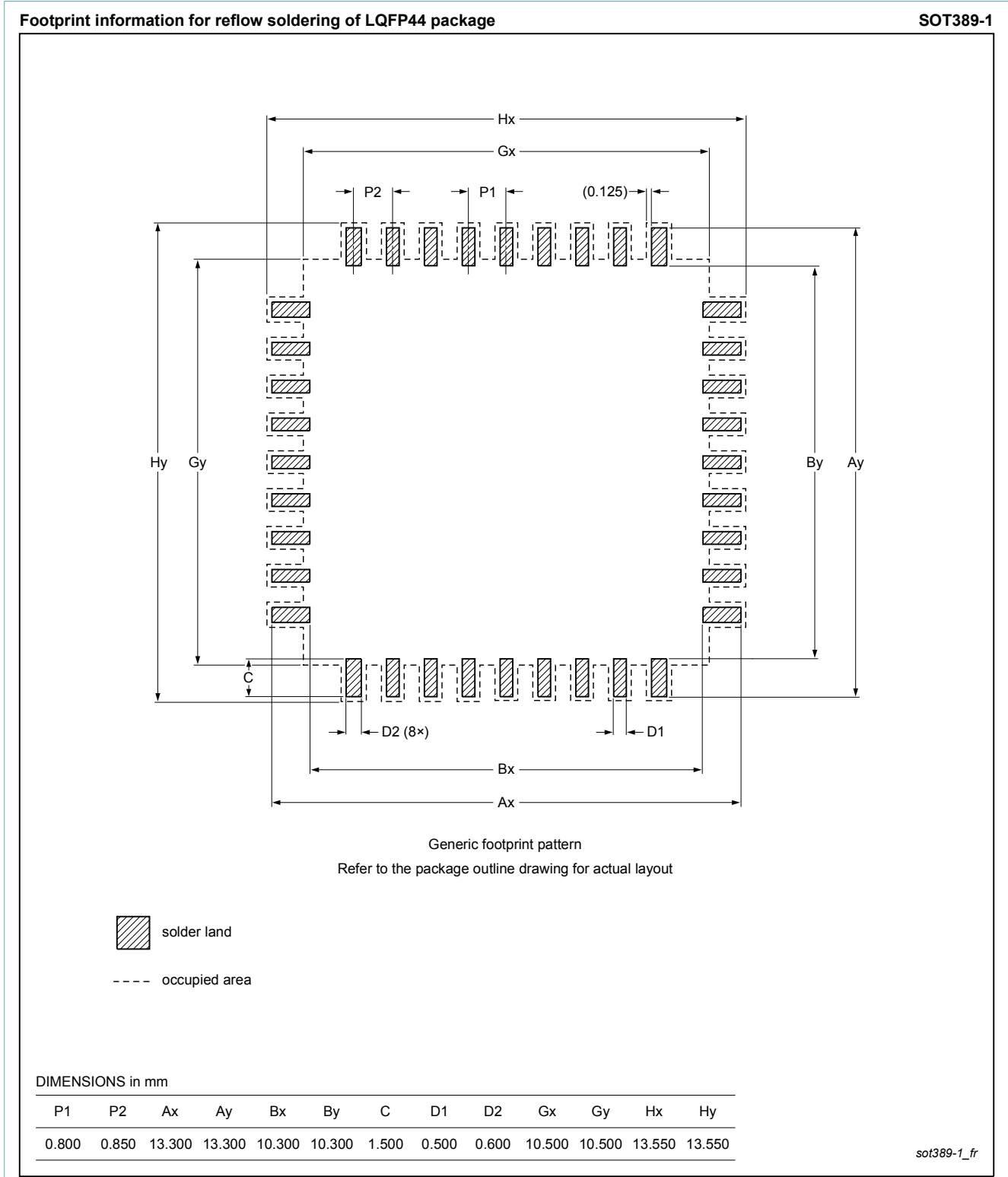
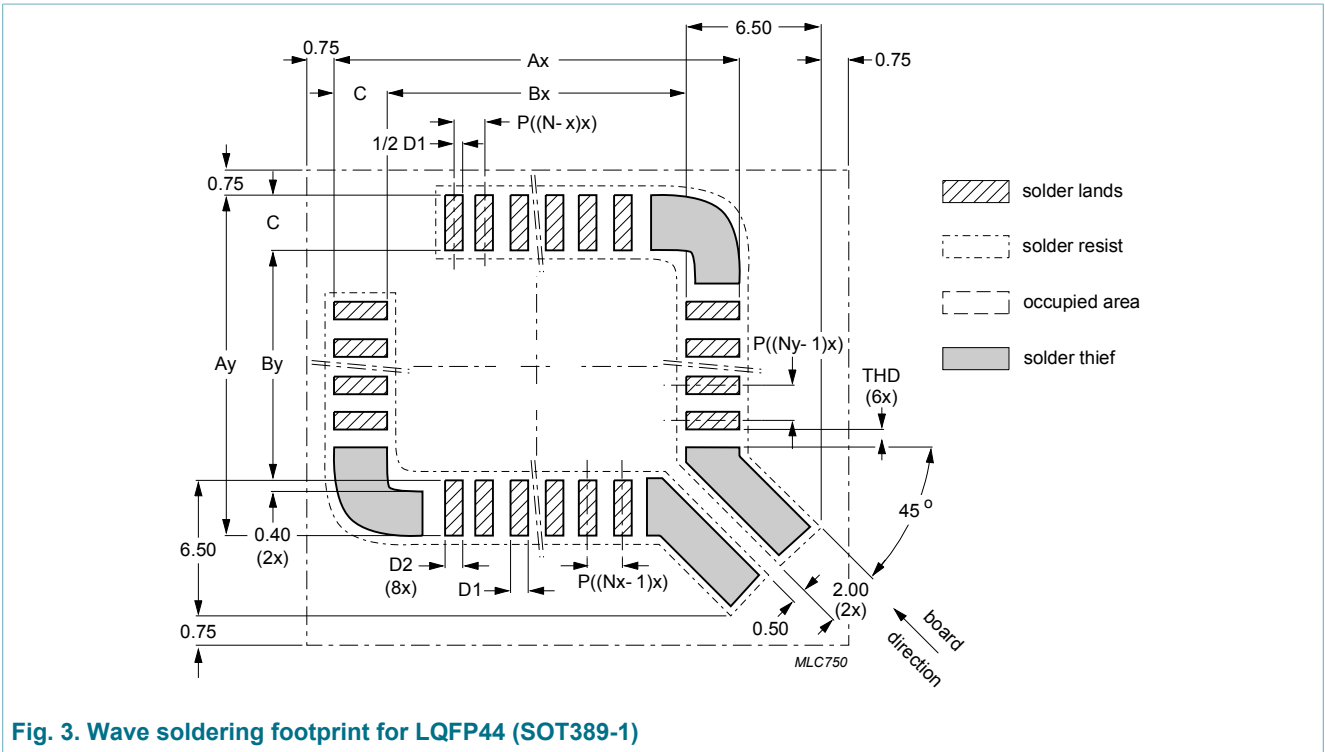


Fig. 2. Reflow soldering footprint for LQFP44 (SOT389-1)

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## 4. Legal information

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